

SERIES 897 • UNIVERSAL SERIAL BUS 3.0 MICRO-B • SURFACE MOUNT SOCKETS

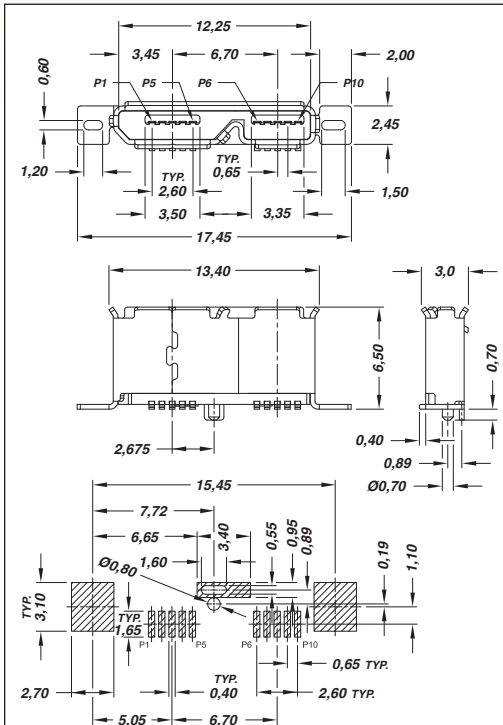


FIG. 1

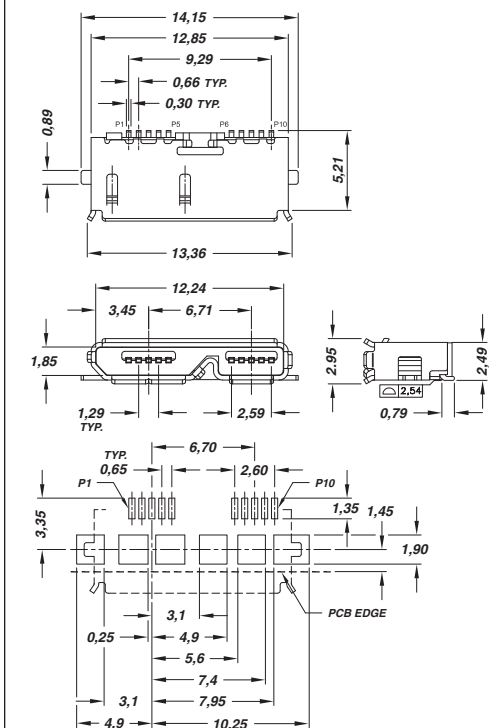


FIG. 2

- USB 3.0 Micro-B receptacles for surface mount
- Reduced mounting space
- Fully shielded
- Fully backwards compatible with USB 2.0
- 10X faster than USB 2.0 and provides optimized power efficiency
- Smaller and lighter than existing USB connectors, for portable & handheld devices
- Packaged on Tape and Reel:
897-10-010-00-300002 - 900 pieces per reel
897-10-010-40-300002 - 1,500 pieces per reel



ORDERING INFORMATION

FIG. 1	Micro Type B Receptacle, Single, Vertical Surface Mount
	897-10-010-00-300002
FIG. 2	Micro Type B Receptacle, Single, Surface Mount
	897-10-010-40-300002

Technical Specifications

Materials:

Terminals: Copper Alloy, Gold Flash over Ni
 Contacts: Copper Alloy, 0,38µm Gold-Plated over Ni
 Shell material: Stainless Steel, Nickel-Plated
 Insulator material: High temperature LCP thermoplastic rated UL94V-0



Ratings:

Voltage: 30VAC (rms)
 Current: 1.5A (Pin 1 and 5), .25A (other pins)
 All housing materials rated for "lead-free" soldering up to 260° C

Electrical:

Contact resistance: 30mΩ max. (Pin 1 and 5)
 50mΩ max. (other pins)
 Insulation resistance: 100MΩ min.
 Dielectric withstanding voltage: 100VAC for 1 minute at sea level

Mechanical:

Random vibration: No discontinuity >1µs per EIA 364-28, cond. V, letter A
 Durability: 10,000 cycles max. per EIA 364-09
 Mating force: 35 Newtons max. per EIA 364-13
 Unmating force: Initial - 10 Newtons min. per EIA 364-13
 After test - 8 Newtons min. per EIA 364-13

Environmental:

Operating Temperature Range: -40°C to +85°C
 Humidity per EIA 364-31, method II, condition A
 Temperature Life per EIA 364-17, condition 3, method A
 Solderability per EIA 364-52, category 2 (260°C for 3 seconds)